

Tool ID:
106
Tool Location:
103
Equipment Information Sheet
Wet/Dry Oxide - B2
Manager: Phil Infante 607-254-4926
Backup: Aaron Windsor 607-254-4831
Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- The furnaces are run at elevated temperatures of 400-1200°C and use flammable, toxic, and corrosive gases.

USAGE RESTRICTIONS

- No changing of gas flows or process parameters without staff approval
- Max process temperature of 1200 C

Minimum Tool Time:
90
minutes

SCHEDULING/SIGN-UP RESTRICTIONS

- Reservation blocks greater than 8 hrs must be cleared by a MOS staff person prior to reserving the time

MATERIALS COMPATIBILITY CATEGORY

Tool Category 1E: Silicon Based Materials and Select Dielectrics

| Allowed | Not Allowed |
|---|---|
| Silicon Based Materials only | No Evaporated or Sputtered Films |
| Si, SiC, SiO ₂ substrates | No Metal or Organic Films |
| All Furnace grown or deposited films | No Glass Substrates |
| PECVD Films | No III/V Compound Semiconductors |
| Select ALD dielectrics (SiO ₂ , SiN, HfO ₂ , HfN) | No High Vapor pressure materials |
| Spin on Glass and Spin on Dopants | Organic/Biology Molecules prepared-with or without Salt buffers |

High Vapor Pressure Metals and Compounds

are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- MOS CLEAN required prior to use
- Only use MOS designated holders, wands and tweezers

Last Updated: 03/20/2019